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FGA60N60UFD 600 V, 60 A Field Stop IGBT

Features

- High Current Capability
- Low Saturation Voltage: V_{CE(sat)} = 1.9 V @ I_C = 60 A
- High Input Impedance
- Fast Switching
- RoHS Compliant

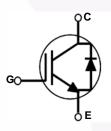
Applications

• Solar Inverter, UPS, Welder, PFC

General Description

Using novel field stop IGBT technology, Fairchild's field stop IGBTs offer the optimum performance for solar inverter, UPS, welder and PFC applications where low conduction and switching losses are essential.





Absolute Maximum Ratings

Symbol	Description		Ratings	Unit	
V _{CES}	Collector to Emitter Voltage		600	V	
V _{GES}	Gate to Emitter Voltage Transient Gate-to-Emitter Voltage		±20	V	
			±30	- V	
I _C	Collector Current	@ T _C = 25°C	120	A	
	Collector Current	@ T _C = 100 ^o C	60	A	
I _{CM (1)}	Pulsed Collector Current	@ T _C = 25°C	180	А	
P _D	Maximum Power Dissipation	@ T _C = 25°C	298	W	
. D	Maximum Power Dissipation	@ T _C = 100 ^o C	119	W	
Т _Ј	Operating Junction Temperature		-55 to +150	°C	
T _{stg}	Storage Temperature Range		-55 to +150	°C	
Τ _L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

Notes:

1: Repetitive test , Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Symbol Parameter		Max.	Unit	
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.33	°C/W	
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	1.1	°C/W	
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W	

March 2015

Part NumberTop MarkPackageFGA60N60UFDTUFGA60N60UFDTO-3P		Package	Packing Method	Reel Size	Tape Width		Quantity	
		Tube	N/A	N/A		30		
Electric	al Cha	aracteristics	of the IC	GBT T _C = 25°C unless otherw	ise noted			
Symbol		Parameter		Test Condition	s Min.	Тур.	Max.	Unit
Off Charac	teristics							-
BV _{CES}	Collector to Emitter Breakdown Voltage		V _{GE} = 0 V, I _C = 250 μA	600	-	_	V	
ΔBV_{CES} / ΔT_J	Temperature Coefficient of Breakdown Voltage		-	V _{GE} = 0 V, I _C = 250 μA	-	0.67	-	V/ºC
I _{CES}		Collector Cut-Off Current		$V_{CE} = V_{CES}, V_{GE} = 0 V$		-	250	μA
I _{GES}		akage Current		$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	±400	nA
On Charac V _{GE(th)}		eshold Voltage		I _C = 250 μA, V _{CE} = V _{GE}	4.0	5.0	6.5	V
GE(m)	• =	oonola tonago		$I_{\rm C} = 60 \text{ A}, V_{\rm GF} = 15 \text{ V}$	-	1.9	2.4	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage		$I_{\rm C} = 60 \text{ A}, V_{\rm GE} = 15 \text{ V},$ $T_{\rm C} = 125^{\circ}\text{C}$	-	2.1	-	v	
Dynamic C	haracter	istics		5				
C _{ies}		apacitance			-	2855	-	pF
C _{oes}	Output (Capacitance		$V_{CE} = 30 V_{V_{GE}} = 0 V_{V_{GE}}$	-	325	-	pF
C _{res}	Reverse	e Transfer Capacita	nce	f = 1 MHz	-	110	-	pF
Switching	Characte	eristics						
t _{d(on)}		n Delay Time			-	23	-	ns
t _r	Rise Tin	-			-	58	-	ns
t _{d(off)}	Turn-Of	f Delay Time		V _{CC} = 400 V, I _C = 60 A,	-	130	-	ns
t _f	Fall Tim	e		R _G = 5 Ω, V _{GE} = 15 V,	-	40	80	ns
E _{on}	Turn-Or	Switching Loss		Inductive Load, $T_C = 25^{\circ}C$	-	1.81	-	mJ
E _{off}	Turn-Of	f Switching Loss			-	0.81	-	mJ
E _{ts}	Total Sw	vitching Loss			-	2.62	-	mJ
t _{d(on)}	Turn-Or	n Delay Time			-	22	-	ns
t _r	Rise Tin	ne		$V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $R_{G} = 5 \Omega, V_{GE} = 15 \text{ V},$ Inductive Load, $T_{C} = 125^{\circ}\text{C}$	-	61	-	ns
t _{d(off)}	Turn-Of	f Delay Time			-	141	-	ns
t _f	Fall Tim	e			-	63	-	ns
Eon	Turn-Or	Switching Loss			°C -	1.92	-	mJ
E _{off}	Turn-Of	f Switching Loss			-	1.23	-	mJ
E _{ts}	Total Sw	vitching Loss			-	3.15	-	mJ
Qg	Total Ga	ate Charge			-	188	-	nC
•	Gate to	Emitter Charge		V_{CE} = 400 V, I _C = 60 A,	-	21	-	nC
Q _{ge}		Ennicer enarge		V _{GE} = 15 V				_

FGA60N60UF
0 0 0 0
600 V, 60
A Fie
ld Stop
IGB1

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Unit
V _{FM}	Diode Forward Voltage	I _⊏ = 30 A	T _C = 25°C	-	2.0	2.6	V
			T _C = 125°C	-	1.8	-	
t _{rr}	Diode Reverse Recovery Time		T _C = 25°C	-	47	-	ns
		I _F = 30 A, di _F /dt = 200 A/μs	T _C = 125 ^o C	-	179		
Q _{rr}	Diode Reverse Recovery Charge	$r_{\rm F} = 30$ Å, $u_{\rm F}/u_{\rm C} = 200$ Å/ μ 3	T _C = 25°C	-	83	-	nC
			T _C = 125 ^o C	-	567	-	





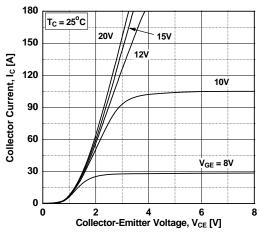


Figure 3. Typical Saturation Voltage Characteristics

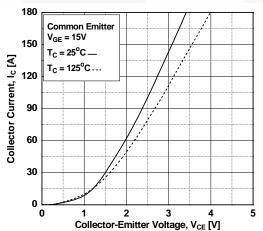


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

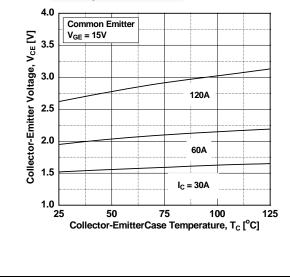


Figure 2. Typical Output Characteristics

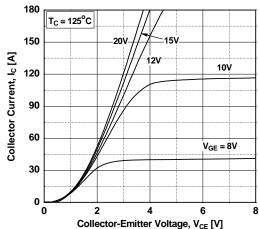


Figure 4. Transfer Characteristics

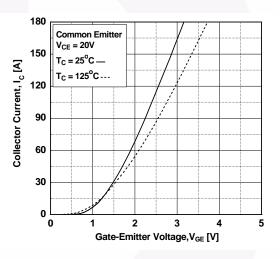
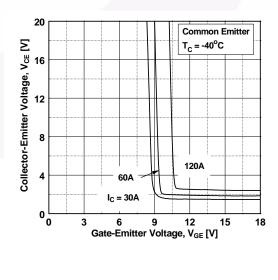
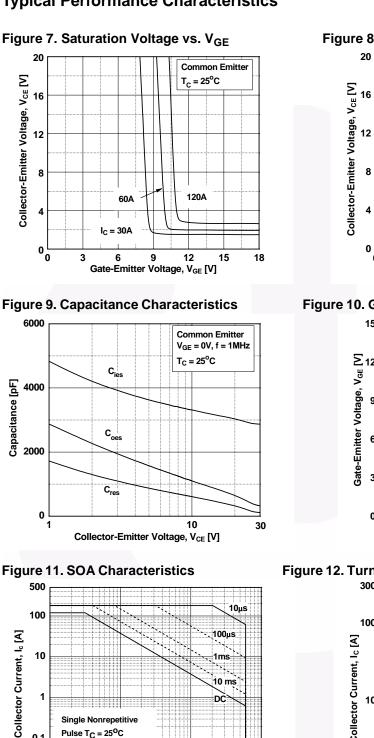


Figure 6. Saturation Voltage vs. V_{GE}



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10 ms

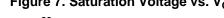
1000

DC

100

Collector-Emitter Voltage, V_{CE} [V]

Typical Performance Characteristics





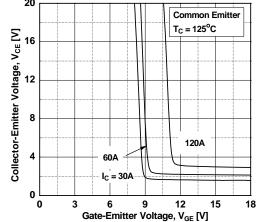
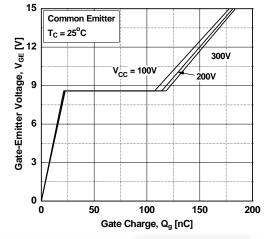
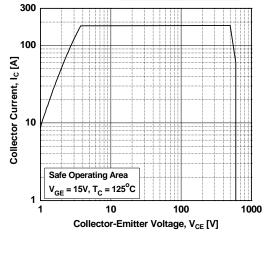


Figure 10. Gate charge Characteristics







1

0.1

0.01

Single Nonrepetitive Pulse T_C = 25^OC

Curves must be derated

10

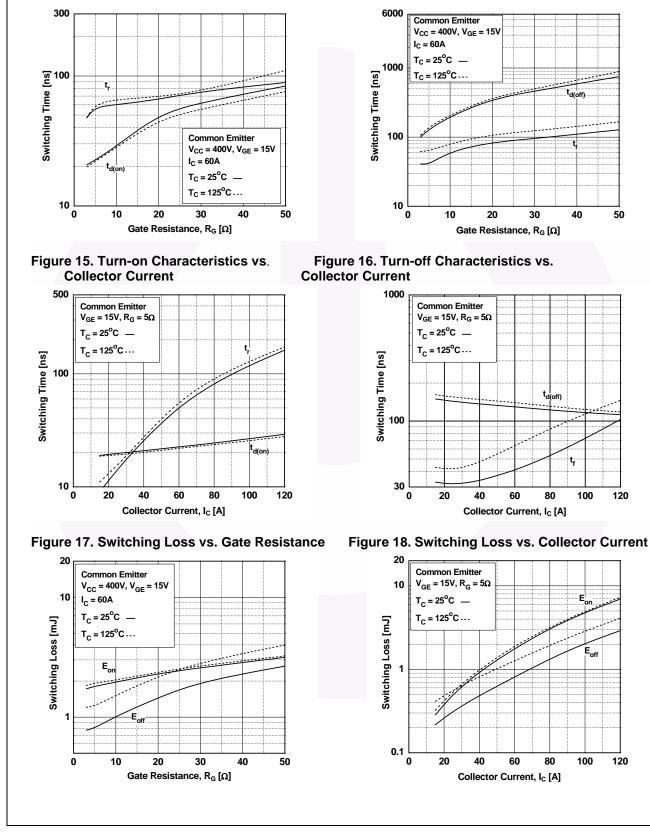
linearly with increase

in temperature

FGA60N60UFD — 600 V, 60 A Field Stop IGBT

Figure 14. Turn-off Characteristics vs.

Gate Resistance



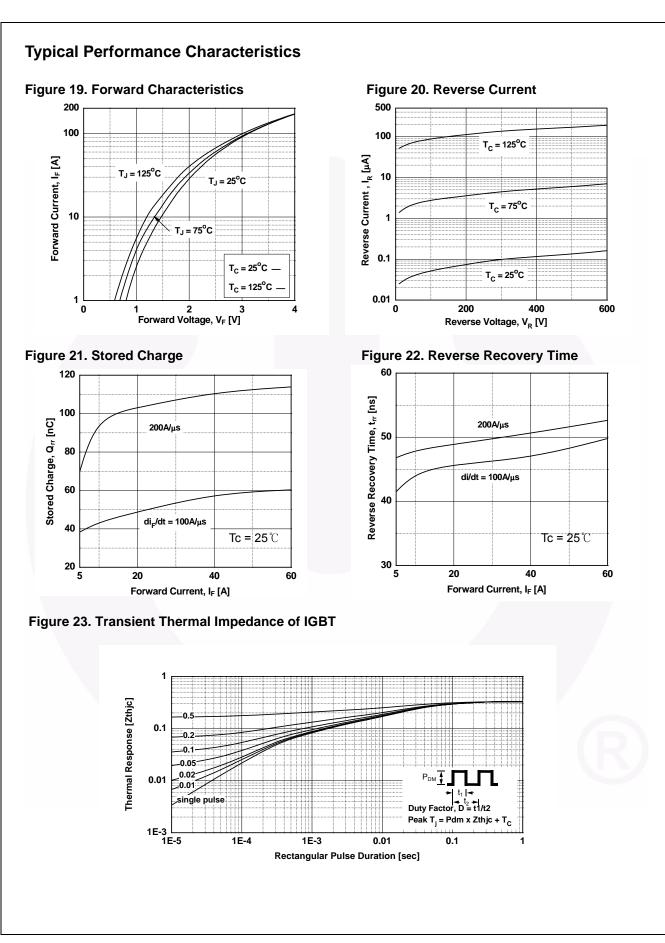
Typical Performance Characteristics

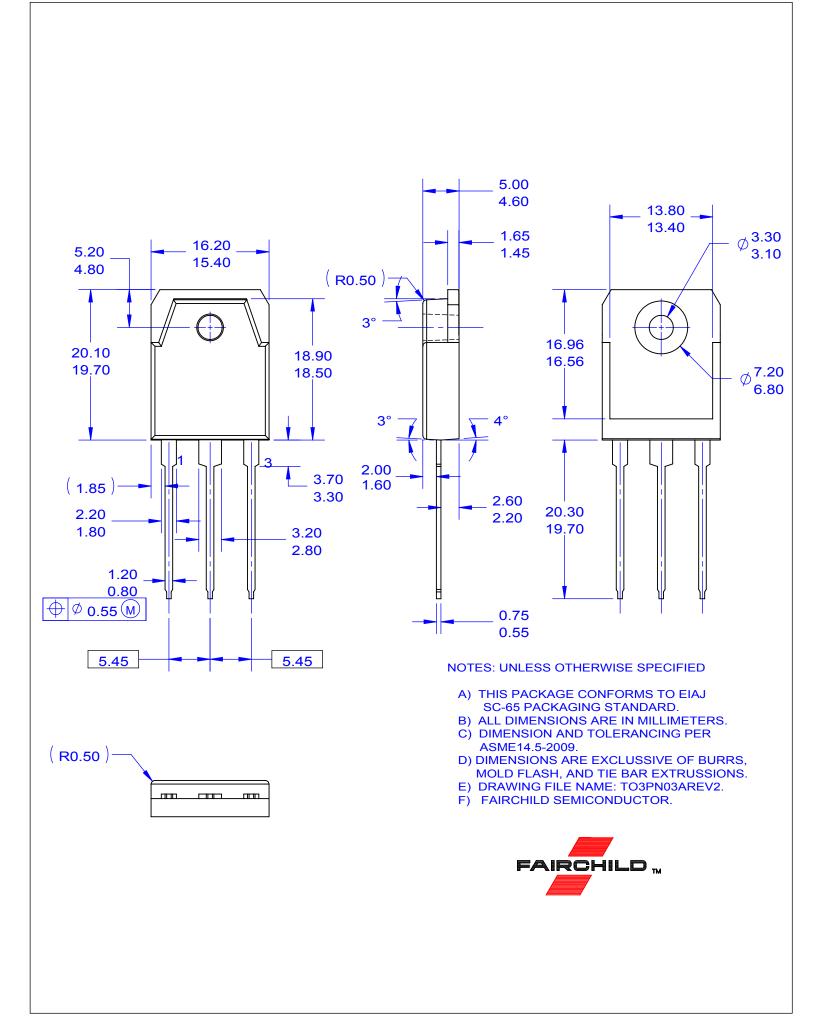
Figure 13. Turn-on Characteristics vs.

Gate Resistance

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